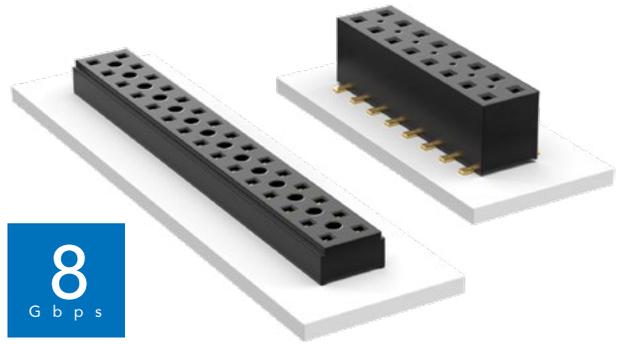


COST-EFFECTIVE & DUAL WIPE SOCKETS

(2.00 mm) .0787" PITCH • TLE/CLT SERIES



TLE

Mates:
TMMH, TMM, MTMM,
MMT, TW, LTMM, ZLTMM,
TCMD, TSH

CLT

Mates:
TMM, TMMH, MTMM,
MMT, TW, TSH

SPECIFICATIONS

TLE

Insulator Material:
Black Liquid Crystal Polymer
Contact Material:
Phosphor Bronze
Plating:
Au over 50 μ" (1.27 μm) Ni
Current Rating (TLE/TMMH):
3.2 A per pin
(2 pins powered)
Operating Temp Range:
-55 °C to +125 °C
Insertion Depth:
(2.08 mm) .082" to
(4.37 mm) .172" with
(0.38 mm) .015" wipe,
pass-through, or
(3.35 mm) .132" min
for bottom entry

CLT

Same as TLE except:
Plating:
Sn or Au over 50 μ" (1.27 μm) Ni
Current Rating (TMMH/CLT):
4.1 A per pin
(2 pins powered)
Insertion Depth:
Top Entry=
(1.40 mm) .055" minimum
Bottom Entry=
(2.57 mm) .101" minimum
(add board thickness for
correct post OAL)
Max Cycles:
100 with 10 μ" (0.25 μm) Au

PROCESSING

TLE

Lead-Free Solderable:
Yes
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-26)
(0.15 mm) .006" max (27-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

CLT

Same as TLE except:
SMT Lead Coplanarity:
(0.10 mm) .004" max (02-25)
(0.15 mm) .006" max (26-34)*
(0.20 mm) .008" max (35-50)*
*(.004" stencil solution
may be available; contact
ipg@samtec.com)

Note:
Some lengths, styles and
options are non-standard,
non-returnable.

| TLE | - 1 | NO. PINS PER ROW | - 01 | PLATING OPTION | - DV | OPTIONS |
|-----|-----|------------------|------|---------------------------------|------|--|
| | | 02 thru 50 | | -G = 10 μ" (0.25 μm) Gold | | -A = Alignment Pin (3 positions minimum) -K = (5.00 mm) .197" DIA Polyimide Film Pick & Place Pad (3 positions minimum) -P = Metal Pick & Place Pad (4 positions minimum) -TR = Tape & Reel Packaging (2-37 positions only) -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (2-37 positions only) |
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| CLT | - 1 | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | - D | OTHER OPTIONS |
|-----|-----|------------------|--|--|-----|---|
| | | 02 thru 50 | -01 = Through-hole -02 = Surface Mount -03 = Through-hole | -F = Gold flash on contact, Matte Tin on tail -L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail -G = 10 μ" (0.25 μm) Gold on contact, Gold flash on tail | | All options require Style -02 -BE = Bottom Entry (Required for bottom entry applications) -A = Alignment Pin (3 positions minimum) Metal or plastic at Samtec's discretion -K = (5.00 mm) .197" DIA Polyimide Film Pick & Place Pad (04 thru 50 only) -P = Pick & Place Pad (4 positions minimum) (Not always necessary for auto placement.) -TR = Tape & Reel (36 positions max) -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (36 positions max) |
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Other Platings

| LEAD STYLE | A |
|------------|-------------|
| -01 | (2.16) .085 |
| -03 | (2.95) .116 |